Features and Benefits

- The control circuit and RGB chip are integrated in a 5050 components, to form an external control pixel.
- 12V power supply voltage can effectively reduce the working current of the whole pixel, reduce the voltage drop of the circuit board, and maximize the consistency of the mixed light when the pixel is transmitted over a long distance.
- Using the built-in signal reshaping circuit to achieve the signal waveform shaping, and no distortion of waveform of signal takes place.
- Each pixel of the three primary color can achieve 256 brightness display, completed 16777216 color full color display, and scan frequency is of 2KHz.
- Cascading port transmission signal by single line.
- Any two point the distance not more than 5m transmission signal without any increase circuit.
- When the refresh rate is 30fps, cascade number are not less than 1024 pixels.
- Send data at speeds of 800Kbps.
- The color of the light is highly consistent, cost-effective.

Applications

- Full-color module, LED full-color soft/hard light bar, LED guardrail tube.
- LED point light source, LED pixel screen, Special-shaped screen.

General description

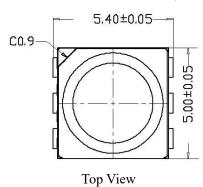
WS2815B is a intelligent control LED light source that the control circuit and RGB chip are integrated in a package of 5050 components. It internal include intelligent digital port data latch and signal reshaping amplification drive circuit. Also include a precision internal oscillator and a voltage programmable constant current control part, effectively ensuring the pixel point light color height consistent. Realize two-way signal transmission, in the case of damage to a single pixel, it does not affect the display of the overall color.

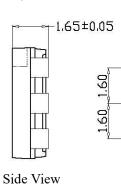
The data transfer protocol use single NZR communication mode. After the pixel power-on reset, the DIN port receive data from controller, the first pixel collect initial 24bit data then sent to the internal data latch, the other data which reshaping by the internal signal reshaping amplification circuit sent to the next cascade pixel through the DO port. After transmission for each pixel, the signal to reduce 24bit. pixel adopt auto reshaping transmit technology, making the pixel cascade number is not limited the signal transmission, only depend on the speed of signal transmission.

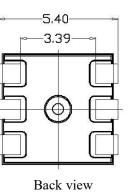
Refresh Frequency updates to **4KHz**, Low Frame Frequency and No Flicker appear in HD Video Camera, It is very suitable for high-speed mobile products.

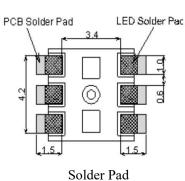
RESET time>280 μ s , it won't cause wrong reset while interruption, it supports the lower frequency and inexpensive MCU.

Mechanical Dimensions(Unit:mm)

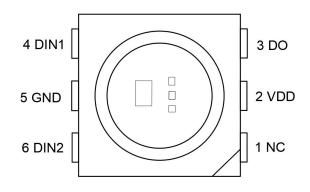








PIN Configuration



PIN Function

NO.	Symbol	PIN	Function description
1	NC	NC	Suspended PIN
2	VDD	LED POWER SUPPLY	LED POWER SUPPLY, connect to "+12V"
3	DO	Data Output	Control data signal output
4	DIN1	Data-1 Input	Control data-1 signal input
5	GND	GROUND	Ground, data & power grounding
6	DIN2	Data-2 Input	Control data-2 signal input

Absolute Maximum Ratings (T_A=25°C, V_{SS}=0V, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Power supply voltage	V _{DD}	+9.5~+13.5	V
Power Consumption	Р	0.1~0.18	W
Logical Input Voltage	VI	-0.3~5.7	V
Working Temperature	Topt	-40~+65	°C
Storage Temperature	Tstg	-40~+85	°C

Parameter	Symbol	Min	Тру	Max	Unit	Conditions
Input current	I_{I}			± 1	μA	$V_I = V_{DD} / V_{SS}$
High Voltage Input	V _{IH}	2.7		5.7	V	D _{IN} , SET
Low Voltage Input	V _{IL}	-0.3		1.5	V	D _{IN} , SET

Electrical Characteristics (T_A=25°C, V_{DD}=12V, V_{SS}=0V, unless otherwise specified)

Switching Characteristics ($T_A=25^{\circ}C$, $V_{DD}=12V$, $V_{SS}=0V$, unless otherwise specified)

Parameter	Symbol	Min	Тру	Max	Unit	Condition
Transmission delay time	t _{PLZ}			300	ns	CL=15pF, DIN→DOUT,RL=10KΩ
Fall time	t _{THZ}			120	μs	CL=300pF, OUTR/OUTG/OUTB
Input capacity	CI			15	pF	

LED Characteristics

Parameter	earameter Symbol			Quiescent (Current<2m	A	Testing Condition DC=12V	
			Mini	Тур	Max	Unit	Working current	
	IV	Red	200	310	400			
Brightness		Green	600	800	1000	mcd	12mA	
		Blue	150	190	300			
		Red	620	623	630			
Wavelength	λd	Green	510	520	520	nm	12mA	
		Blue	465	471	475			

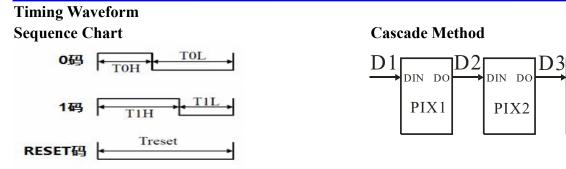
Data Transfer Time

ТОН	0 code, high voltage time	220ns~380ns
T1H	1 code, high voltage time	580ns~840ns
TOL	0 code, low voltage time	900ns~5000ns
T1L	1 code, low voltage time	600ns~5000ns
RES	Frame unit, low voltage time	>280µs
Tdata	Data cycling time	≥1.25µs

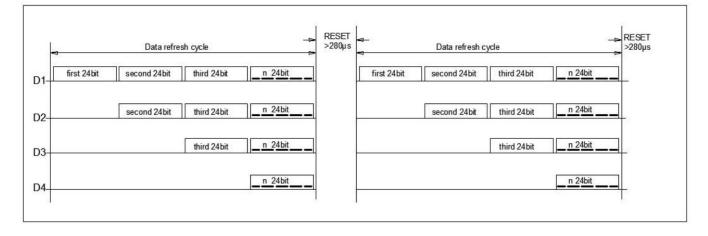
DIN DO

PIX3

D4



Data Transmission Method



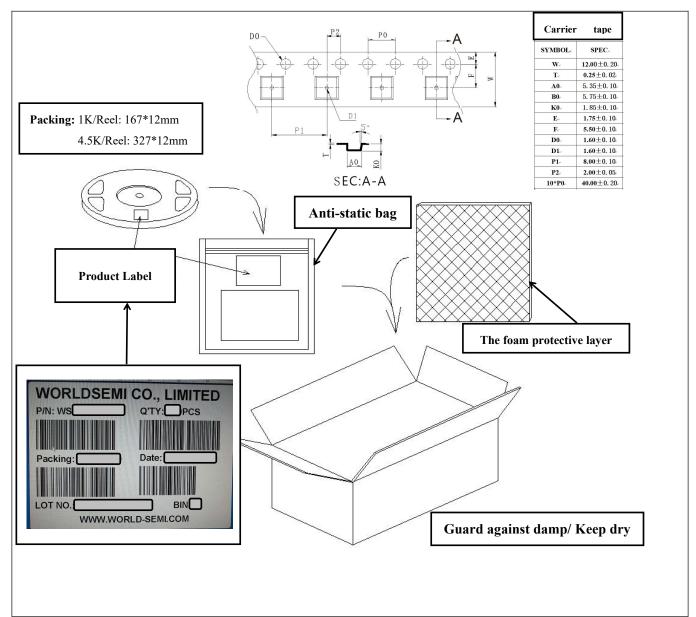
Note: The data of D1 is send by MCU, and D2, D3, D4 through pixel internal reshaping amplification to transmit.

Composition of 24bit Data

G7 G6 G5 G4 G3 G2 G1 G0 R7 R6 R5 R4 R3 R2 R1 R0 B7 B6 B5 B4 B3 B2 B1 B0																				-				
	G7	G6	G5	G4	(i i i	G2	G1	G0	R7	R6	R5	R4	R3	R2	R1	R0	B7	B6	B5	B4	В3	B2	B1	B0

Note: Data transmit in order of GRB, high bit data at first.

Packing Standard



Top SMD LED Using Instructions

1. Summary

To make the best use of WORLDSEMI's LED, please refer to the below precautions, they are of same usage method as other electronic components.

2. Cautions

2.1. Dust & Cleaning

The surface of the LED is encapsulated with modified epoxy resin because it plays a very good role in protecting the optical performance and aging resistance. The modified epoxy resin is easy to stick with dust and must be kept clean. When there's a certain amount of dust on the surface of the LED, it won't affect brightness, but dust proof should be taken care of. Promoting the use of unsealed package in preference to others and the assembled LEDs should be placed in a clean container.

Avoid using the organic solvents to clean the dust on the LED surface and it's necessary to confirm whether the cleaning fluid will dissolve the LED.

Do not clean the LEDs by the ultrasonic. Some parameters affecting the LED performance must be evaluated if have no alternative but to the ultrasonic cleaning method, such as ultrasonic power, baking time and assembly conditions, etc.

2.2. Moisture-proof packaging

TOP SMD LEDs are moisture sensitive components. LEDs are packaged in aluminum foil bag to prevent the from absorbing moisture during transport and storage. A desiccant is placed in the bags to absorb moisture. If the LED absorbs moisture, then it evaporates and expands when in reflow process, which may break the colloid from the bracket and damage the optical performance of LED. For this reason, moisture-proof packaging is to prevent the from absorbing moisture during transport and storage. The moisture resistance rating of WORLDSEMI's LED is: LEVEL 5a.

MSL Level	Workshop Life						
	Time	Conditions					
LEVEL1	Unlimited	≤30°C/85%RH					
LEVEL2	1 Year	≤30°C/60%RH					
LEVEL2a	4 Weeks	≤30°C/60%RH					
LEVEL3	168 Hours	≤30°C/60%RH					
LEVEL4	72 Hours	≤30°C160%RH					
LEVEL5	48 Hours	≤30°C/60%RH					
LEVEL5a	24 Hours	≤30°C/60%RH					
LEVEL6	Take-out and Use immediately	≤30°C/60%RH					

Tabel I - IPC/JEDEC J-STD-020 Moisture/Reflow Sensitivity Classification

2.3 SMT Requirement:

2.3.1 It is recommended to unpack the LED before SMT and put the whole roll into the oven for dehumidification and drying (baking at 70 ~ 75 °C for \ge 24h);

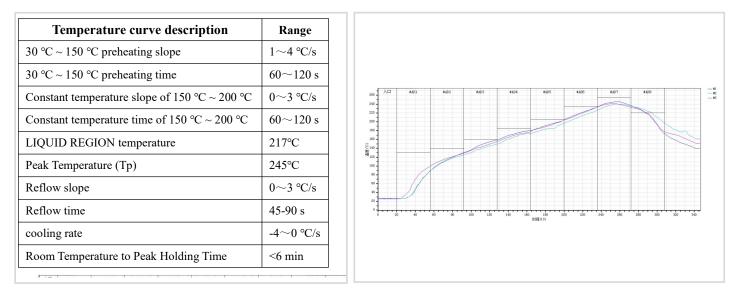
2.3.2 The product is taken out of the oven to the completion of high-temperature soldering (including multiple high-temperature operations/operations such as reflow soldering, tin immersion, wave soldering, and heating maintenance), and the time period is controlled within 24 hours (under the conditions of T<30°C, RH<60%);

2.3.3SMT shall be completed as soon as possible for LED pastes on PCBA after printing solder paste, and it is recommended not to exceed 1H;

2.3.4 Bulk LEDs such as production surplus, machine throwing materials, and maintenance materials cannot be used directly if they are exposed to the air for a long time. It is recommended to dehumidify and dry before use. Whole roll baking: $70 \sim 75^{\circ} \text{C}^* \ge 24 \text{H}$ or bulk material baking: $120^{\circ} \text{C}^* 4 \text{H}$.

3. SMT Reflow

Refer to the parameters listed below, the experimental results prove that the TOP SMD LED meets the JEDEC J-STD-020C standards. As a general guideline, it is recommended to follow the SMT reflow temperature curve recommended by the solder paste manufacturer.



Remarks: All temperatures referred are measured on the surface of the package body.

4. Assembly Precautions

1. Clip the LED from its side.	2. Neither directly touch the gel surface with the hand or	3. Not to be double stacked, it may damage its internal circuit.	4. Can not be stored in or applied in the acidic sites of
Side.	sharp instrument, it may	may damage its internal circuit.	PH<7.
	damage its internal circuit.		111 .</td
			KPH7

Modify Record

Version №	Status Bar	Modify Content Summary	Date	Reviser	Approved
V1.0	Ν	New	20180820	Shen JinGuo	Yin HuaPing
V1.1	М	Brightness, Timing and SMT cautions	20190507	Shen JinGuo	Yin HuaPing
V1.2	М	Product description	20200519	Shen JinGuo	Yin HuaPing
V1.3	М	Product description	20210401	Dong Le	Yin HuaPing
V1.4	М	Using instructions	20220531	Yu XingHui	Yin HuaPing
V2.0	М	IC upgraded, parameters updated	20221020	Yu XingHui	Yin HuaPing
V2.1	М	Add power consumption	20221201	Yu XingHui	Yin HuaPing
V2.2	М	Timing sequence modified	20230315	Hu Jin	Yu XingHui

Remarks: Initial version: V1.0; Version number plus "0.1" after each revision;

Status bar: N--New, A--Add, M--Modify, D--Delete.